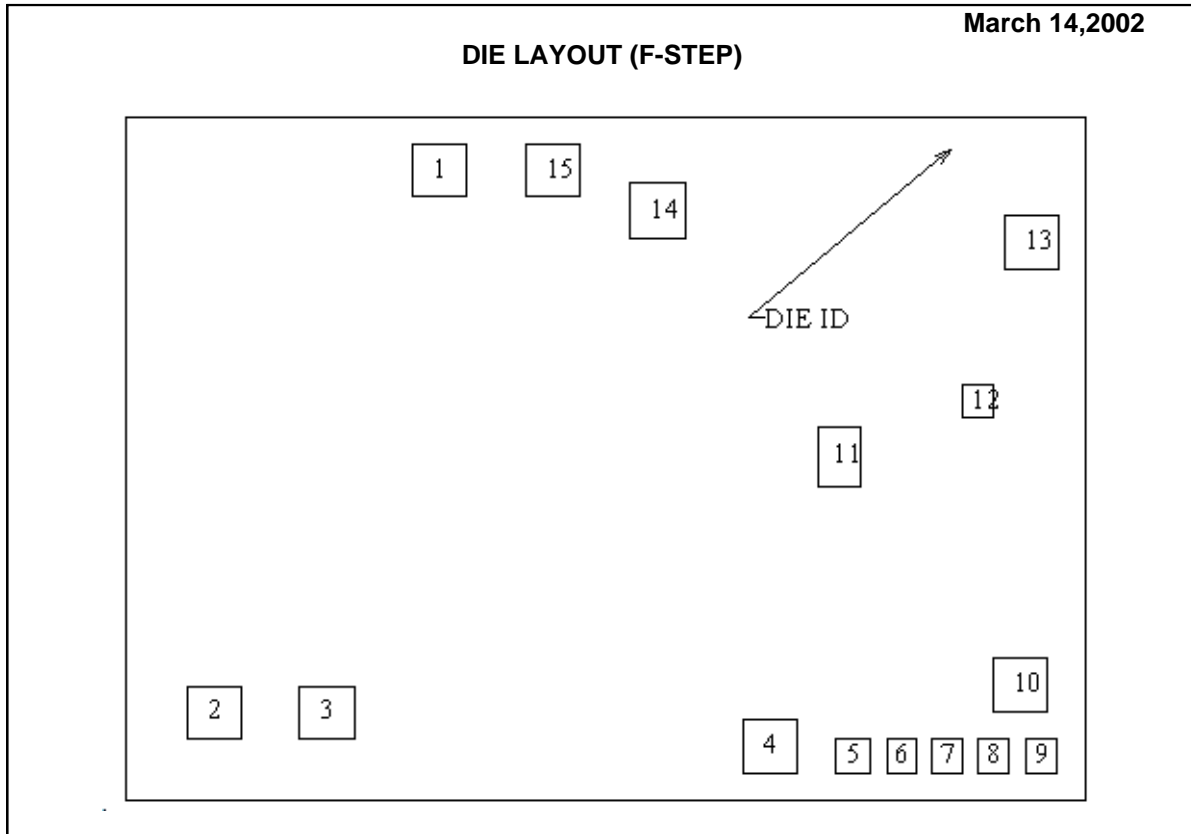


**LM2941-ADJ MDC MWC**  
**1A LOW DROPOUT ADJUSTABLE REGULATOR**



**DIE/WAFER CHARACTERISTICS**

Fabrication Attributes		General Die Information	
Physical Die Identification	LM1940F	Bond Pad Opening Size (min)	140µm x 135µm
Die Step	F	Bond Pad Metalization	ALUMINUM
Physical Attributes		Passivation	VOM NITRIDE
Wafer Diameter	150mm	Back Side Metal	TI,NI,AG
Die Size (Drawn)	1753µm x 2464µm 69mils x 97mils	Back Side Connection	Floating
Thickness	254µm Nominal		
Min Pitch	118µm Nominal		

**Special Assembly Requirements:**

**Note: Actual die size is rounded to the nearest micron.**

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Die Bond Pad Coordinate Locations (F -Step)						
(Referenced to die center, coordinates in $\mu\text{m}$ ) NC = No Connection						
SIGNAL	PAD#	X/Y CORRDINATES		PAD SIZE		
NAME	NUMBER	X	Y	X	Y	
VIN	1	-427	741	140	x	135
OUTPUT	2	-1007	-652	140	x	130
OUTPUT	3	-717	-652	140	x	130
GND	4	422	-739	140	x	139
NC	5	636	-763	90	x	90
NC	6	760	-763	77	x	90
NC	7	878	-763	77	x	90
NC	8	997	-763	77	x	90
NC	9	1120	-763	77	x	90
ADJ	10	1063	-582	139	x	139
NC	11	601	7	109	x	153
NC	12	957	148	78	x	88
ON/OFF	13	1094	555	140	x	140
GND	14	133	637	140	x	140
VIN	15	-137	741	140	x	135

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